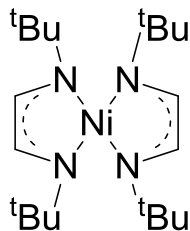


Catalog # 28-0225 Bis(1,4-di-t-butyl-1,3-diazabutadienyl)nickel(II) Ni(DAD)₂, min. 98% (99.999%-Ni) PURATREM



Technical Notes:

1. Used for the vapor deposition (ALD and CVD) of nickel-containing films.
2. The atomic layer deposition of nickel metal films is described using bis(1,4-di-tert-butyl-1,3-diazabutadienyl)nickel(II) and formic acid as precursors.
3. Precursors for CVD and ALD processes for obtaining nickel, nickel silicide or nickel nitride thin films.

References:

1. Winter, Charles H.; Knisley, Thomas J., U.S. **2016**, US 9255327 B2 20160209
2. Winter, Charles H.; Knisley, Thomas J., U.S. Pat. Appl. Publ. **2016**, US 20160152650 A1 20160602
3. Klesko, Joseph P.; Kerrigan, Marissa M.; Winter, Charles H. *Chem. Mater.*, **2016**, *28*, 700-703.
4. Knisley, Thomas J.; Saly, Mark J.; Heeg, Mary Jane; Roberts, John L.; Winter, Charles H., *Organometallics* **2011**, *30*, 5010-5017.
5. Lansalot-Matras, Clement; Gatineau, Julien; Jurcik, Benjamin J., Jr., PCT Int. Appl. **2013**, WO 2013046157 A1 20130404.